

Sandwich-structured intelligent power module for building into appliances includes a printed circuit board for a logical unit with a recess fitted with a power substrate on a cooling plate connected by a wire bonding technique.

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Abstract

A printed circuit board (5) for a logical unit has a recess (6) fitted with a power substrate (2) on a cooling plate (8) and connected electrically to the logical unit by means of a wire bonding technique. A power unit's components (1) including power semiconductors fit on the power substrate. The logical unit's IC and SMD components (3,4) fit on the printed circuit board.

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